

Title (en)  
LED LEADFRAME PACKAGE, LED PACKAGE USING THE SAME, AND METHOD OF MANUFACTURING THE LED PACKAGE

Title (de)  
LED-LEITERRAHMENPAKET, LED-PAKET DAMIT UND VERFAHREN ZUR HERSTELLUNG DES LED-PAKETS

Title (fr)  
BOÎTIER DEL POUR GRILLE DE CONNEXION, GRILLE DE CONNEXION UTILISANT LE BOÎTIER DEL, ET PROCÉDÉ DE FABRICATION DU BOÎTIER DEL

Publication  
**EP 2406835 A4 20130918 (EN)**

Application  
**EP 10750967 A 20100224**

Priority  
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• US 38140909 A 20090310

Abstract (en)  
[origin: WO2010104276A2] A LED lead frame package, a LED package using the LED lead frame package, and a method of manufacturing the LED package. In the manufacture of the LED package, a liquid transparent resin material is disposed over at least two ring-shaped protrusions having a sharp upper edge and inclined sidewalls and at least one ring-shaped groove formed between two of the at least two ring-shaped protrusions, and thus a sealing layer having a convex curvature may be easily formed by using surface tension in one process.

IPC 8 full level  
**H01L 33/62** (2010.01); **H01L 33/64** (2010.01)

CPC (source: EP)  
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Citation (search report)  
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• See references of WO 2010104276A2

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